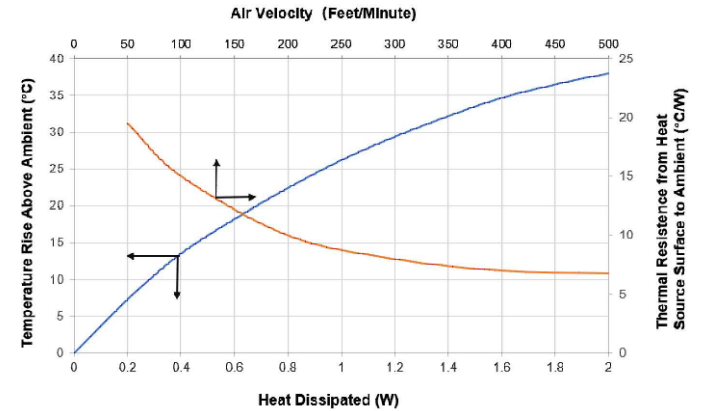
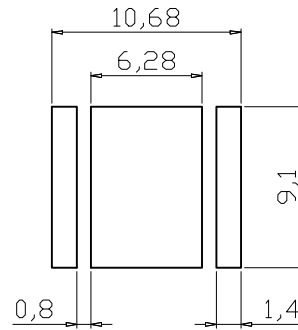
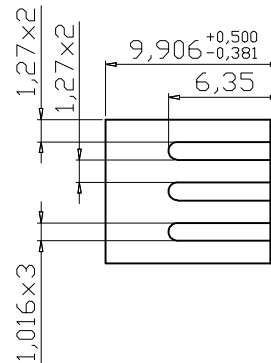
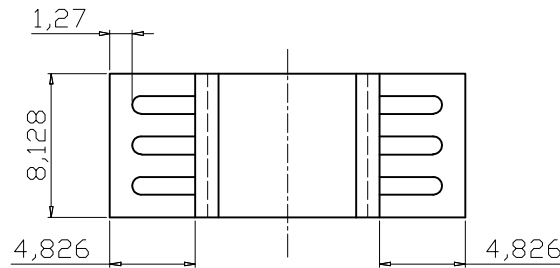


⑥ Recommended PCB solder layout footprint  
all dimension in mm



⑨ Thermal Resistance Diagram

Material :Copper T=0.6mm;  
Finished: Bright Tin Plated;  
Unmarked round angle R is 0.75



Option	Packaging	Thermal resistance(K/W)
V-1100-SMD/B	⑤ Tape&Reel ③ 400 pcs/reel	25
V-1100-SMD/B-L	Bulk ⑦ 625 pcs/pe bag	25

**RoHS compliant**

Unit:mm

Scale	Free	⑨	Add the thermal resistance diagram	23.09.2023	Segal	Date	Name	Description: Stamping heat sink	
TOLERANCE		⑧	Add the packing information on page 2	01.07.2020	Segal	Drawn	11.08.2009	Dean	
		⑦	Update packaging qty	19.03.2018	Amy	Approved	23.09.2023	Segal	
UNIT	±0.3	⑥	Add PCB layout	14.10.2014	Amy			ASSMANN WSW-No. <b>V-1100-SMD/Bx</b>	
DIM	TOL	⑤	Change the packing qty	10.01.2014	Amy			Drawing-No. <b>ASS 0855 HS</b>	
UNIT	±0.5°	④	Change production plant	26.09.2013	Amy			Customer-No.	
Angle	TOL	Id.	Modification	Date	Name	A company of		SHEET 1 / 2	

1

2

3

4

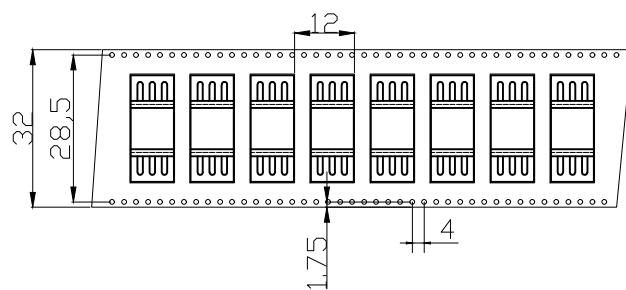
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6

7

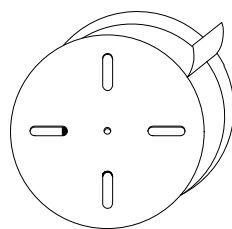
A

V-1100-SMD/B packing way



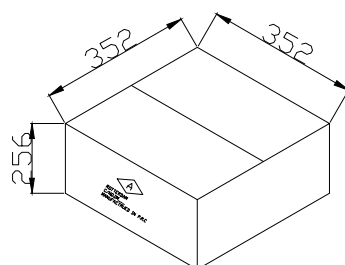
B

C



Material: PS

D

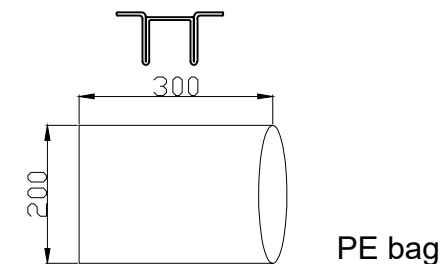


E

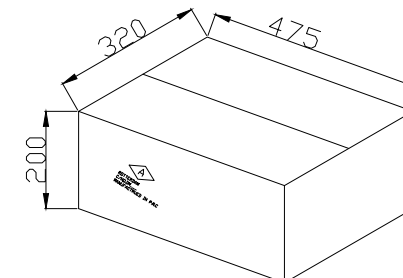
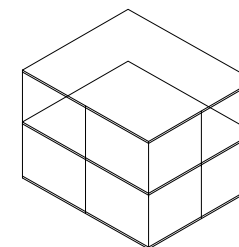
F

1. Carton size: 352x352x256mm;
2. 400pcs/Reel, 4 Reels/Carton, 1600pcs/Carton;
3. N.G.: 4.8KG, W.G.: 6.0KG.

V-1100-SMD/B-L packing way



PE bag





G

H

RoHS compliant

Unit:mm

Scale	Free	⑨	Add the thermal resistance diagram	23.09.2023	Segal		Date	Name	Description: Stamping heat sink	
TOLERANCE		⑧	Add the packing information on page 2	01.07.2020	Segal	Drawn	11.08.2009	Dean	ASSMANN WSW-No. <b>V-1100-SMD/Bx</b>	
		⑦	Update packaging qty	19.03.2018	Amy	Approved	23.09.2023	Segal		
UNIT	±0.3	⑥	Add PCB layout	14.10.2014	Amy					
DIM	TOL	⑤	Change the packing qty	10.01.2014	Amy	 A company of 		Drawing-No. <b>ASS 0855 HS</b>		rev09
UNIT	±0.5°	④	Change production plant	26.09.2013	Amy			Customer-No.		SHEET 2 / 2
Angle	TOL	Id.	Modification	Date	Name					

A

B

C

D

E

F

G

H

1

2

3

4

5

6

7